SDAS027B - APRIL 1984 - REVISED JANUARY 1995

- 3-State I/O-Type Read-Back Inputs
- Bus-Structured Pinout
- True Logic Outputs
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (N) 300-mil DIPs

description

This 8-bit latch is designed specifically for storing the contents of the input data bus and providing the capability of reading back the stored data onto the input data bus.

The eight latches are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs.

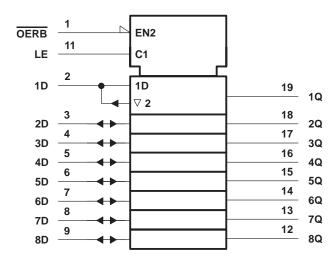
(TOP VIEW) **OERB** 20 🛮 V_{CC} 1D 2 19 1Q 2D 3 18 2Q 17 3Q 3D 4D 5 16 4Q 15 5Q 5D 14 6Q 6D 13**∏** 7Ω 7D 8 8D 9 12 8Q 10 11 🛮 LE GND

DW OR N PACKAGE

Read back is provided through the output-enable (OERB) input. When OERB is taken low, the data present at the output of the data latches is allowed to pass back onto the input data bus. When OERB is taken high, the output of the data latches is isolated from the D inputs. OERB does not affect the internal operation of the latches; however, precautions should be taken not to create a bus conflict.

The SN74ALS990 is characterized for operation from 0°C to 70°C.

logic symbol†

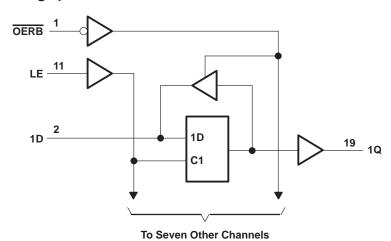


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

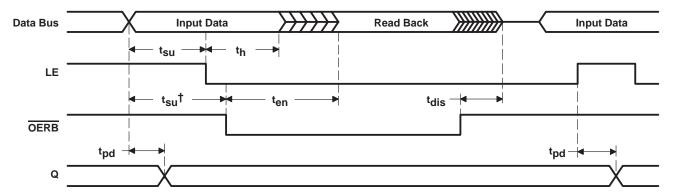


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logic diagram (positive logic)



timing diagram



[†] This setup time ensures that the read-back circuit will not create a conflict on the input data bus.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I (OERB and LE)	7 V
Voltage applied to D inputs	5.5 V
Operating free-air temperature range, T _A	0° C to 70° C
Storage temperature range	−65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



SDAS027B - APRIL 1984 - REVISED JANUARY 1995

recommended operating conditions

			MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	V
VIH	High-level input voltage		2			V
VIL	Low-level input voltage		T		0.8	V
1	High lovel output output	Q			-2.6	mA
ЮН	High-level output current	D			-0.4	mA
la.	Low lovel output outropt	Q			24	mA
OL	Low-level output current	D				IIIA
t _W	Pulse duration, LE high		10			ns
	Catua tima	Data before LE↓	10			
tsu	Setup time	Data before OERB↓	10			ns
th	Hold time, data after LE↓		5			ns
TA	Operating free-air temperature		0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		PARAMETER TEST CONDITIONS				MAX	UNIT
VIK		$V_{CC} = 4.5 V,$	$I_{I} = -18 \text{ mA}$			-1.2	V
.,	All outputs	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2			.,
VOH	Q	V _{CC} = 4.5 V,	$I_{OH} = -2.6 \text{ mA}$	2.4	3.2		V
		V 45V	I _{OL} = 4 mA		0.25	0.4	
\ _{\\\\\}	D	V _{CC} = 4.5 V	I _{OL} = 8 mA		0.35	0.5	V
VOL		V 45V	I _{OL} = 12 mA		0.25 0		V
	Q	V _{CC} = 4.5 V	I _{OL} = 24 mA		0.35	0.5	
1.	OERB, LE	V	V _I = 5.5 V			0.1	mA
Ч	D inputs	V _{CC} = 5.5 V	V _I = 7 V			0.1	IIIA
	OERB, LE	V00 - 5 5 V	V _I = 2.7 V			20	
ΊΗ	D inputs‡	V _{CC} = 5.5 V,	V = 2.7 V			20	μΑ
	OERB, LE	V00 - 5 5 V	\\\ 0.4 \\			-0.1	mA
IIL	D inputs‡	V _{CC} = 5.5 V,	.5 V, $V_{l} = 0.4 V$			-0.1	IIIA
IO§		V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	mA
		<u>VCC</u> = 5.5 V,	Outputs high		27	50	mA
Icc		OERB high	Outputs low		40	70	IIIA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] For I/O ports (Q_A thru Q_H), the parameters I_{IH} and I_{IL} include the off-state output current.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

SN74ALS990 8-BIT D-TYPE TRANSPARENT READ-BACK LATCH

SDAS027B - APRIL 1984 - REVISED JANUARY 1995

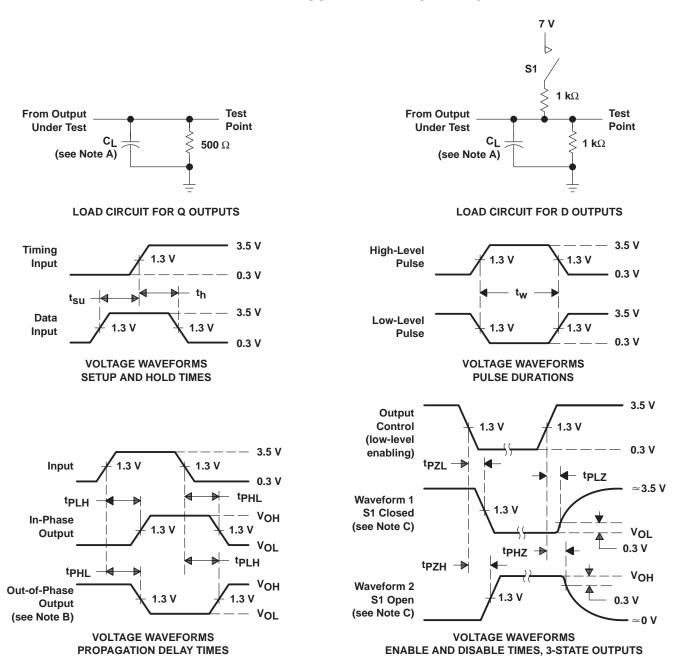
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 C _L = 50 pF T _A = MIN to	UNIT	
			MIN	MAX	
t _{PLH}	D		4	17	20
^t PHL	ט	Q	5	24	ns
^t PLH	LE		6	26	ns
^t PHL	LL	Q	8	26	115
t _{en} ‡	OERB	D	4	21	ns
t _{dis} §	OERB	D	4	19	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

t_{en} = t_{PZH} or t_{PZL} t_{dis} = t_{PHZ} or t_{PLZ}

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. When measuring propagation delay times of 3-state outputs, switch S1 is open.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_{Γ} = t_{f} = 2 ns, duty cycle = 50%.

Figure 1. Load Circuits and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS990DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS990	Samples
SN74ALS990N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS990N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION



TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS990DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

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*All dimensions are nominal

	Device	Package Type		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
I	SN74ALS990DWR	SOIC	DW	20	2000	367.0	367.0	45.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

ı	Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
	SN74ALS990N	N	PDIP	20	20	506	13.97	11230	4.32

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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